

February 17, 2022

ADEKA CORPORATION

ADEKA to Construction a New Plant for Materials used of Cutting-Edge Logic IC in Taiwan

ADEKA Corporation (President and Chief Executive Officer: Hidetake Shirozume) has decided to construct a new plant for materials used of cutting-edge logic IC at ADEKA FINE CHEMICAL TAIWAN CORP., our consolidated subsidiary. The plant is an overseas production site for semiconductor materials, following ADEKA KOREA CORP. in Korea.

The semiconductor market is expected to grow to a market size of 1 trillion dollars in 2030, to expand 5G communications and realize an advanced ICT society including AI and the metaverse. As such, there are demands for further technological innovations in semiconductors. Of these, since the miniaturization of logic IC, which perform controls and arithmetic operations, is quick, it is expected that innovation in technologies for production processes and materials will emerge around 2023, when the EUV process will be introduced to the semiconductor photolithography process in earnest. The materials used will also be purified more, and it is expected that they will be replaced with new materials with stronger quality control standards.

ADEKA considers technological innovation of logic IC as a business opportunity and has decided to construct a new plant in Taiwan, a center for R&D and production. Triggered by this plant construction, we will enter the logic IC business in Taiwan in earnest with the aim of expanding our semiconductor business. Going forward, we will aim to expand the product lineups of materials for cutting-edge semiconductors by entering the field of materials for 3D mounting technologies, which increases the degree of integration of semiconductors.



▲ ADEKA FINE CHEMICAL TAIWAN CORP.

ADEKA will contribute to realizing an advanced ICT society by providing cutting-edge semiconductor materials.

◆ Outline

Location	ADEKA FINE CHEMICAL TAIWAN CORP. (NO.32 GONGYE 6TH RD., ANNAN DISTRICT TAINAN)
Investment value	2.5 billion yen
Total floor area	3,068 m ²
Schedule	Construction commencement : August 2022 Commencement of commercial operation: April 4

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Supplementary notes:

1: Miniaturization of logic IC and ADEKA's cutting-edge materials

Miniaturization of logic IC is advancing, aiming to downsize semiconductor chips and improve arithmetic throughput. For further miniaturization, an increase of the number of integrated transistors is required, which means mounting as many chips as possible on a single silicon wafer. Therefore, microfabrication of wiring is critical.

Our materials are used in wiring processes (ALD film formation) for leading-edge logic IC to which an EUV exposure process is applied. Our ALD materials are seen as indispensable for miniaturization.

2: Information about ADEKA's Electronics and IT Materials Business

The Electronics and IT Materials Business provides *SOZAI* (our Excellent Value; products, technologies and services), which means indispensable cutting-edge materials for the development of ICT society in the semiconductor and display fields.

Its product portfolio consists of highly profitable products that have the highest global market share. For instance, *ADEKA ORCERA series*, the high-dielectric material series, has a global market share of 50% or more for the application for DRAM, the most advanced semiconductor memory.

ADX 2023 (from FY2021 to FY2023), the mid-term management plan of ADEKA Group, positions the next-generation ICT field as one of the important fields to enhance scale dramatically.

■ Contacts

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